

Expertise

**Expert Opinion of the Notified Body on the Conformity Assessment
according to Article 10.5 of R&TTE Directive 1999/5/EC**

PHOENIX TESTLAB
EU Identification Number **0700**

Recognised by  Bundesnetzagentur

BNetzA-bs-02/51-55

Expertise No.	16-210199
Certificate Holder	Shenzhen Huaptec Co.,Ltd.
Address	5th FL, E BLDG, Sogood Science Park, Hangkong Road, Xixiang, Bao'an, Shenzhen, China
Product Description	Wireless Signal Booster/ Mobile Signal Booster/RF Repeater; with GSM
Brand Name / Model Name	Huaptec / F23H-ED-70-75, F20H-ED-65-70, F17H-ED-65-65, F13H-ED-60-65, F10H-ED- 60-65

Opinion on the Essential Requirements

Article 3.1a): Health and Safety	No remarks
Article 3.1b): Electromagnetic Compatibility	No remarks
Article 3.2: Effective Use of the Radio Spectrum	No remarks

CE-marking

Marking Example (Class 2)

CE 0700 

This certificate is issued in accordance with the Directive 1999/5/EC of the European Parliament and the Council on radio equipment and telecommunications terminal equipment and the mutual recognition of their conformity dated 9th March 1999 and is only valid in conjunction with the following annex (2 pages).

Blomberg, 28 January 2016

Place, Date of Issue



Signed by Alan Lane
Notified Body

Technical description

Frequency Range	Downlink: 925 - 960 MHz; 1805 - 1880 MHz Uplink: 880 - 915 MHz; 1710 - 1785 MHz
Transmitted Power	Downlink: Max. 23 dBm Uplink: Max. 17 dBm
Operational temperature range Device	-10 ~ 40 degree Celsius
Operational temperature range Power adaptor	40 degree Celsius

Technical Construction File (TCF):

Technical documentation according to Annex II sub clause 4:

- | | |
|---|---|
| <input checked="" type="checkbox"/> User Manual | <input checked="" type="checkbox"/> Operational Description |
| <input checked="" type="checkbox"/> Block Diagram | <input checked="" type="checkbox"/> Circuit Diagram |
| <input checked="" type="checkbox"/> Parts Placement | <input checked="" type="checkbox"/> PCB-Layout |
| <input checked="" type="checkbox"/> Parts List | |

Hardware Version: F25H0-2S-V04

Software Version: V1.0

Applied Standards and Test Reports

Specification	Laboratory	Test Report Number
EN 60950-1:2006+A11:2009+A1:2010+A12:2011+A2:2013	EMTEK (Shenzhen) CO., LTD.	ES151221044S Ver.1.0
EN 60950-1:2006+A11:2009+A1:2010+A12:2011+A2:2013	Shenzhen LCS Compliance Testing Laboratory Ltd.	LCS1512141121S
EN 50385:2002	Shenzhen LCS Compliance Testing Laboratory Ltd.	LCS1512141114E
EN 301 489-1 V1.9.2 EN 301 489-8 V1.2.1	Shenzhen LCS Compliance Testing Laboratory Ltd.	LCS1512141113E
EN 300 609-4 V10.2.1	Shenzhen LCS Compliance Testing Laboratory Ltd.	LCS1512141112E

Further Documents

EU Declaration of Conformity, 2 pages, 2016-01-06.

Product Similarity Declaration, 1 page, 2015-12-10.



Opinion on the Essential Requirements:

The basis of this Expertise is the Technical Construction File (TCF). If the TCF includes test reports issued by laboratories accredited to the standard ISO/IEC 17025, the test results of these reports are considered as a basis for the conformity assessment of the Notified Body.

Article 3.1a): Health and Safety:

- Conform.

Article 3.1b): Electromagnetic Compatibility:

- Conform.

Article 3.2: Effective Use of the Radio Spectrum:

- Conform.

General Remarks:

- This conformity assessment is limited to the essential requirements of the R&TTE Directive. Only products fulfilling all essential requirements of all applicable new approach directives may be placed on the market and put into service. Products in compliance with all provisions of the applicable directives providing for the CE marking must bear this marking.
- Before putting a product on the market which uses non harmonised frequencies (Class 2) the national authorities of the member states have to be notified.
- The user shall be informed by the person placing the product onto the market if an individual confirmation by network operators may be required for using in EC member states.
- The Technical Construction File should include the following technical documentation additionally:
 - Sub board of parts placement
 - Sub board of PCB layers